**EEJA RAD PLATER #1 – ASPCM POR**

1. CHEM FILL with Cu VMS bath
2. RECIRC at OCP for 30min to condition the tool

             - Adjust rotation to **25rpm**

             - Adjust flow rate to **3-3.5L/min**

1. Make additive additions **15mL/L Acc, 7mL/L Supp, 8mL/L Lev**
2. RECIRC at OCP for 5min
3. Plate blanket wafer: **Constant current mode 1.5A, 11min (max voltage setting)**
4. Measure Cu thickness to ensure within specification
5. Process ASPCM lot

              - Prewet: 2min vacuum + 1min vacuum and water (Vacuum setting 5)

              - Plate: **Constant current mode 1.5A, 11min (max voltage setting)**

              - Measure Cu thickness